

Title (en)
HARDENING MASS CONTAINING URETHANE GROUPS COMPRISING SILYLATED POLYMERS AND THE USE OF SAME IN SEALANTS AND ADHESIVES, BINDING AND/OR SURFACE MODIFICATION AGENTS

Title (de)
HÄRTBARE MASSE ENTHALTEND URETHANGRUPPEN AUFWEISENDE SILYLIERTE POLYMERE UND DEREN VERWENDUNG IN DICHT- UND KLEBSTOFFEN, BINDE- UND/ODER OBERFLÄCHENMODIFIZIERUNGSMITTELN

Title (fr)
MATIÈRE DURCISSABLE COMPRENANT DES GROUPES URÉTHANE PRÉSENTANT DU POLYMÈRE SILYLÉ ET SON UTILISATION DANS DES ADHÉSIFS ET PRODUITS D'ÉTANCHÉITÉ, DES LIANTS ET/OU AGENTS MODIFICATEURS DE SURFACE

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Application
EP 17154775 A 20100716

Priority
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• EP 10169796 A 20100716

Abstract (en)
[origin: EP2289972A1] Hardenable materials (I) containing urethane group-containing products (II) obtained by the reaction of (a) compound(s) with one or more isocyanate groups with (b) compound(s) with one or more alkoxyisilyl groups plus at least one hydroxyl group, optionally in presence of (c) catalyst(s), (d) other component(s) which react with the reaction products, especially compounds with functional groups with protic hydrogen, and (e) other component(s) which do not react with the products or the starting materials. Independent claims are included for (1) a method (M1) for bonding surfaces together by applying (I) to at least one of the surfaces or between both surfaces and then hardening the material (2) a method (M2) for sealing, bridging or filling surfaces, cracks or gaps by applying (I) and hardening the material (3) a method (M3) for the surface-modification of particles or sheet materials by adding crosslinking catalysts to (I), applying to the particles or surface (in the pure state or from a suitable solvent, or from emulsion) and then reacting with covalent or physical bonding.

Abstract (de)
Härtbare Masse enthaltend Urethangruppen aufweisende silylierte Polymere und deren Verwendung in Dicht- und Klebstoffen, Binde- und/oder Oberflächenmodifizierungsmitteln.

IPC 8 full level
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